



# TECHCONNECT INNOVATION CHALLENGE

## **SUBMIT AN INNOVATION**

### ***PITCH TO THE LARGEST FUNDING PIPELINE ON THE PLANET!***

Launch your electrifying journey into the future of innovation! Join the world's largest multi-sector commercialization program for emerging deep technologies. Pitch your groundbreaking innovations and connect with top-tier corporate, investment, military and federal leaders for partnering, licensing and investment opportunities. Whether you're a startup, university TTO, federal lab, or federal awardee, seize the moment. Submit your commercially viable innovation now and connect with the largest gathering of tech-scouts and funding offices worldwide.

### **SECTORS:**

Advanced Materials  
Advanced Manufacturing  
Energy & Sustainability  
Electronics & Microsystems  
Biotech & Medical  
AI & Digital Transformation  
Space, Defense, Mobility

### **WHO SHOULD APPLY**

Our industry and government tech scouts seek cutting-edge, commercially viable innovations, including technologies from: University and research labs with actionable IP and spinouts; startups seeking investment, licensing, partnering actions; and Federal awardees (i.e., SBIR, OTA DARPA, ARPAE, ARPAH, BARDA).

## **HOW TO PARTICIPATE**

Submit your technology for review. If selected, you will confirm your position and pitch to a panel of investment, industry, and national security leadership in Austin, Texas at the conference.

## **PITCH & SHOWCASE**

TechConnect will notify finalists in early April. Selected companies must confirm their participation through either a registration or showcase fee, as indicated upon notification.

**Pitch dates:** June 9-11, 2025

**Challenge location:** JW Marriott | Austin, TX

Please contact the University of South Florida Technology Transfer office representative for submission – Karla Schramm at [kschramm@usf.edu](mailto:kschramm@usf.edu)